

**INTEGRATED INTERCONNECT AND METHOD
OF MANUFACTURE THEREFOR
ABSTRACT OF THE DISCLOSURE**

An integrated interface structure for a nested body to provide an
5 electrical connection. The interface structure includes nested bond pads which
electrically interface with leads. The nested bond pads are fabricated on a
microstructure to provide an interface to drive circuitry for transducer elements
of a slider or head supported by the microstructure.

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